

ABSTRACT

A constant temperature chamber to be disposed in a handler for use with an IC tester is provided which is capable of preheating semiconductor devices to be measured to a preset temperature uniformly and in a short time. A rotary stage adapted to rotate with semiconductor devices to be measured loaded thereon is disposed in the bottom of the constant temperature chamber enclosed by thermal insulation walls. A heater is disposed in the upper portion of the constant temperature chamber. An axial-flow fan is positioned between the heater and the rotary stage. Further, a tubular flow-rectifying member is disposed surrounding and in proximity to the outer periphery of the axial-flow fan. A gas flow produced by rotatively driving the axial-flow fan is rectified by the flow-rectifying member with no turbulences occurring, and a circulating rectified gas flow is thereby formed from the axial-flow fan to pass through the rotary stage, and then advancing radially outwardly through between the undersurface of the rotary stage and the bottom thermal insulation wall of the constant temperature chamber, followed by rising in swirling streams along the interior of the thermal insulation walls of the chamber and flowing back to the axial-flow fan.

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